Soder-Wick® Rosin Flux Desoldering Braid

Product Description

Soder-Wick® offers the state of the art in desoldering technology. Soder-Wick® is designed for today's heat sensitive electronic components using lighter mass, pure copper braid construction that allows for better thermal conductivity, even at low temperatures. Soder-Wick® responds faster than conventional desoldering braids thereby minimizing overheating and preventing PCB damage.

Soder-Wick Rosin has the fastest desoldering action in the industry. Flux residues must be cleaned after the rework process.

Typical Applications

Soder-Wick® desoldering braid safely removes solder from:

- Thru-hole Components
- SMT Pads and BGA Pads
- Micro Circuits
- Terminals
- Lugs and Posts
- Identification Script

Static Dissipative Packaging

Soder-Wick is packaged on Static Dissipative bobbins in 5 and 10-foot lengths to minimize the risk of damage associated with static electricity. The static dissipative bobbins qualify as electrostatic discharge protective per MIL-STD-1686C and MIL-HDBK-263B, and meet the static delay rate provision of MIL-B-81705C.

Typical Product Data and Physical Properties

Flux Type:	Rosin Grade WW, Type "R" Patented No Clean High Temperature No Clean
Specifications:	ANSI/IPC J STD-004 MIL-F-14256 F
Shelf Life:	2 years
RoHS Compliant	Yes

Part #	Size Inches	Color	Size Metric
1	.030"	White/Gray	0.8mm
2	.060"	Yellow	1.5mm
3	.080"	Green	2.0mm
4	.110"	Blue	2.8mm
5	.145"	Brown	3.7mm
6	.210	Red	5.3mm

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Usage Instructions

For industrial use only. Read SDS carefully prior to use.

1) Choose a Soder-Wick® braid width equal to or slightly larger than the pad or connection.
2) Choose a solder iron tip equal to or slightly larger than the pad or connection.
3) Set temperature of iron between 600-750°F.
4) Place wick on solder joint and place tip of hot iron on top of wick.
5) As solder becomes molten, the color of the wick will change from copper to silver.
6) Remove wick and iron from joint simultaneously once color change has stopped.
7) The component lead / pad is now clean and free from solder.
8) Clip and discard used portion of the wick
9) If needed, clean PCB with CircuitWorks Flux Remover Pen and remove soils with a ControlWipes absorbent wipe.

Availability

VacuPak™ Packaging

The VacuPak™ Can contains ten five-foot bobbins in a vacuum sealed can. This package provides the highest level of cleanliness and freshness. Great for tool kit storage.

Part #	Size
SW18015	1
SW18025	2
SW18035	3
SW18045	4
SW18055	5

Soder-Wick Is Designed To Meet or Exceed the Following:

- MIL-F-14256F, Type R
- NASA-STD-8739.3
- DOD-STD-883E, Method 2022
- ANSI/IPC J STD-004, Type ROL0
- BELLCORE TR-NWT-000078
- ANSI/IPC J SF-818

HELPFUL HINTS:

Water Soluble Users: Use Soder-Wick Unfluxed 70 or 75 Series to dip in water soluble flux and then desolder normally.

Ball Grid Array: Use #6 red Soder-Wick with a large tipped iron to remove solder from a number of BGA pads all at once.

Technical and Application Assistance

Chemtronics provides a technical hotline to answer your technical and application related questions.
The toll free number is: 1-800-TECH-401.

Note:

This information is believed to be accurate. It is intended for professional end users having the skills to evaluate and use the data properly. CHEMTRONICS does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.

Part #	Size	Length	Part #	Size	Length	Part #	Size	Length	Part #	Size	Length	Part #	Size	Length
80-1-5	1	5’	80-1-10	1	10’	50-1-25	1	25’						
80-2-5	2	5’	80-2-10	2	10’	50-2-25	2	25’	50-2-100	2	100’	50-2-500	2	500’
80-3-5	3	5’	80-3-10	3	10’	50-3-25	3	25’	50-3-100	3	100’			
80-4-5	4	5’	80-4-10	4	10’	50-4-25	4	25’	50-4-100	4	100’			
80-5-5	5	5’	80-5-10	5	10’	50-5-25	5	25’						
80-6-5	6	5’				50-6-25	6	25’						